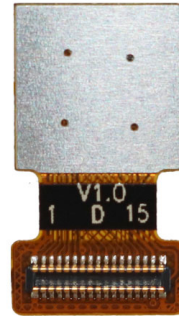


YDS-ENT-IMX214 V1.0

13MP Sony IMX214 MIPI Interface Auto Focus Camera Module



Front View



Back View

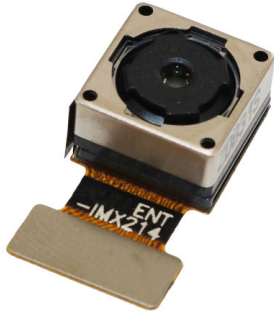
Specifications

Camera Module No.	YDS-ENT-IMX214 V1.0
Resolution	13MP
Image Sensor	IMX214
Sensor Type	1/3.06"
Pixel Size	1.12 um x 1.12 um
EFL	3.85 mm
F.NO	2.20
Pixel	4224 x 3136
View Angle	74.4°(DFOV) 62.7°(HFOV) 48.7°(VFOV)
Lens Dimensions	8.50 x 8.50 x 5.37 mm
Module Size	16.07 x 9.00 mm
Module Type	Auto Focus
Interface	MIPI
Auto Focus VCM Driver IC	FP5510
Lens Model	YDS-LENS-50013A1
Lens Type	650nm IR Cut
Operating Temperature	-20°C to +70°C
Mating Connector	BM20B(0.8)-30DS-0.4V(51)



YDS-ENT-IMX214 V1.0

13MP Sony IMX214 MIPI Interface Auto Focus Camera Module



Top View



Side View



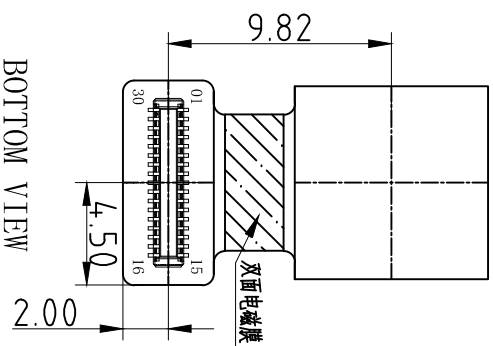
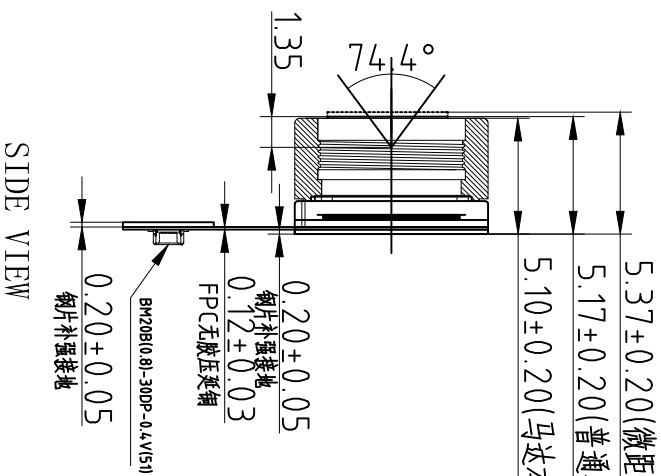
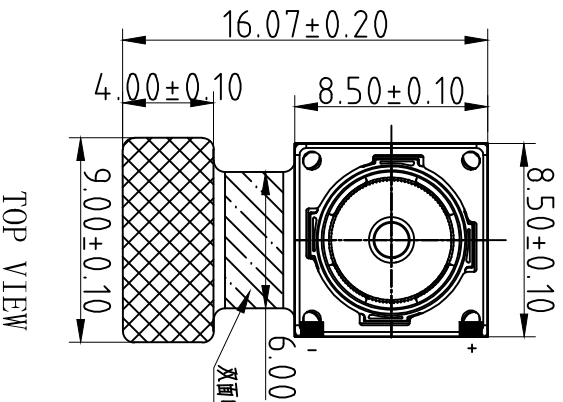
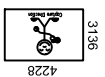
Bottom View



Mating Connector

RoHS

1	MDN1
2	MDP1
3	DGND
4	MDN3
5	MDP3
6	DGND
7	MDN0
8	MDP0
9	DGND
10	MDN2
11	MDP2
12	DGND
13	MCN
14	MCP
15	AGND
16	AF_VDD 2.8V
17	AVDD 2.8V
18	DVDD 1.05V
19	D0VDD 1.8V
20	NC
21	XCLK
22	NC
23	NC
24	SCL
25	SDA
26	RESET
27	NC
28	NC
29	NC
30	NC



NOTE:
 1.The device slave address:0x20(w);0x21(r)
 2.Driver IC:FP5510

Parameters:

1、Sensor specification:

Image Sensor: IMX214
 Pixel: 1.12umx1.12um
 Lens Type: 1/3.06
 Important Voltage Description: DVDD1.05V
 (External power supply);

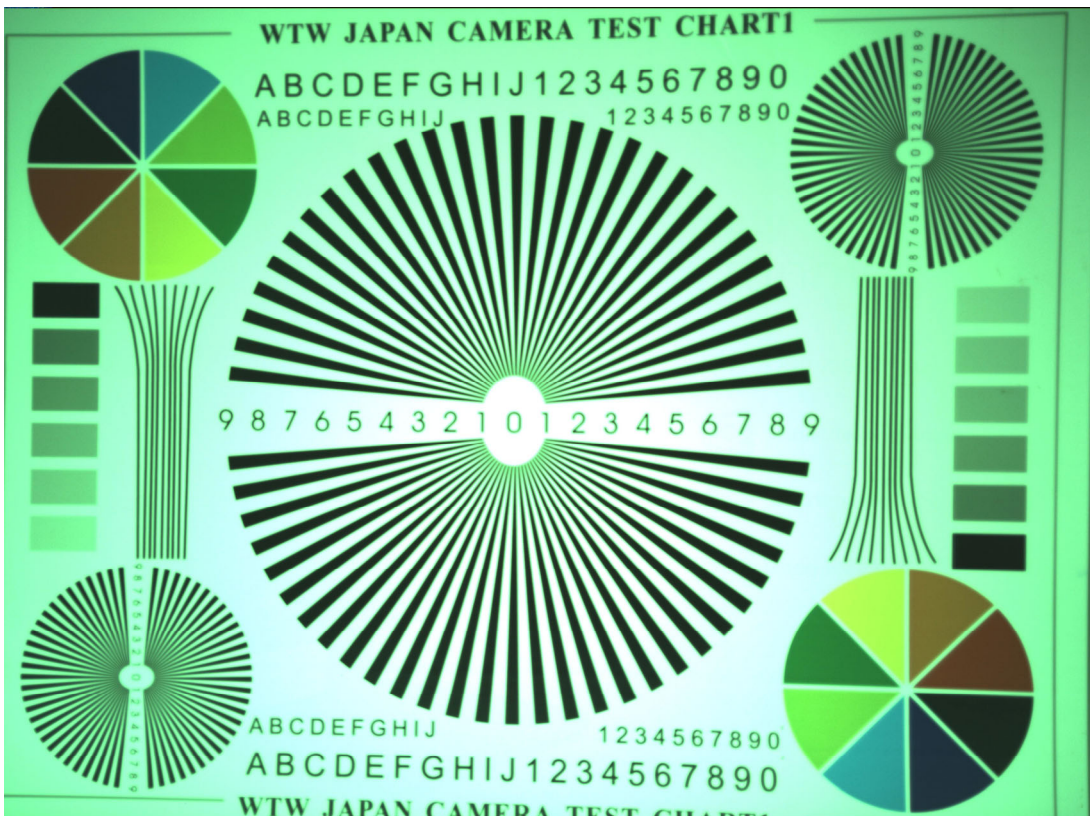
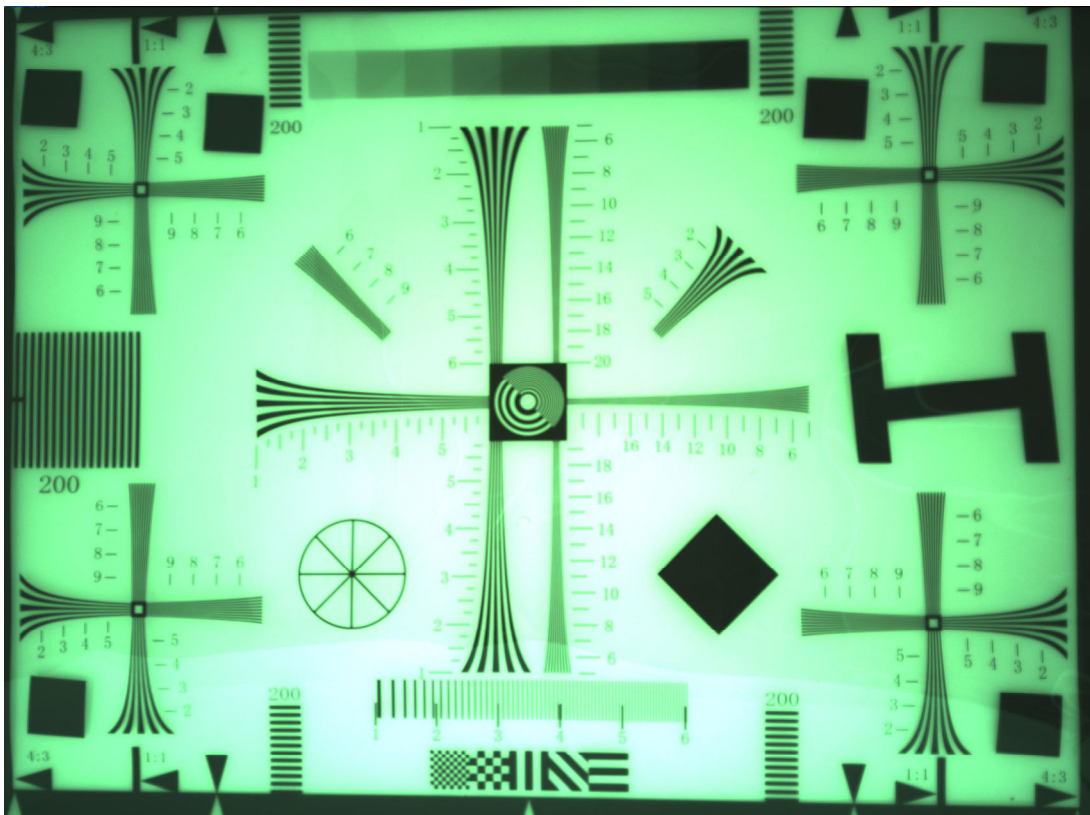
2、Lens specification:

FOV: 74.4°
 F/NO.: 2.2±5%
 TV distortion: <1.5%
 Focal length: 3.81mm
 Composition: 5P

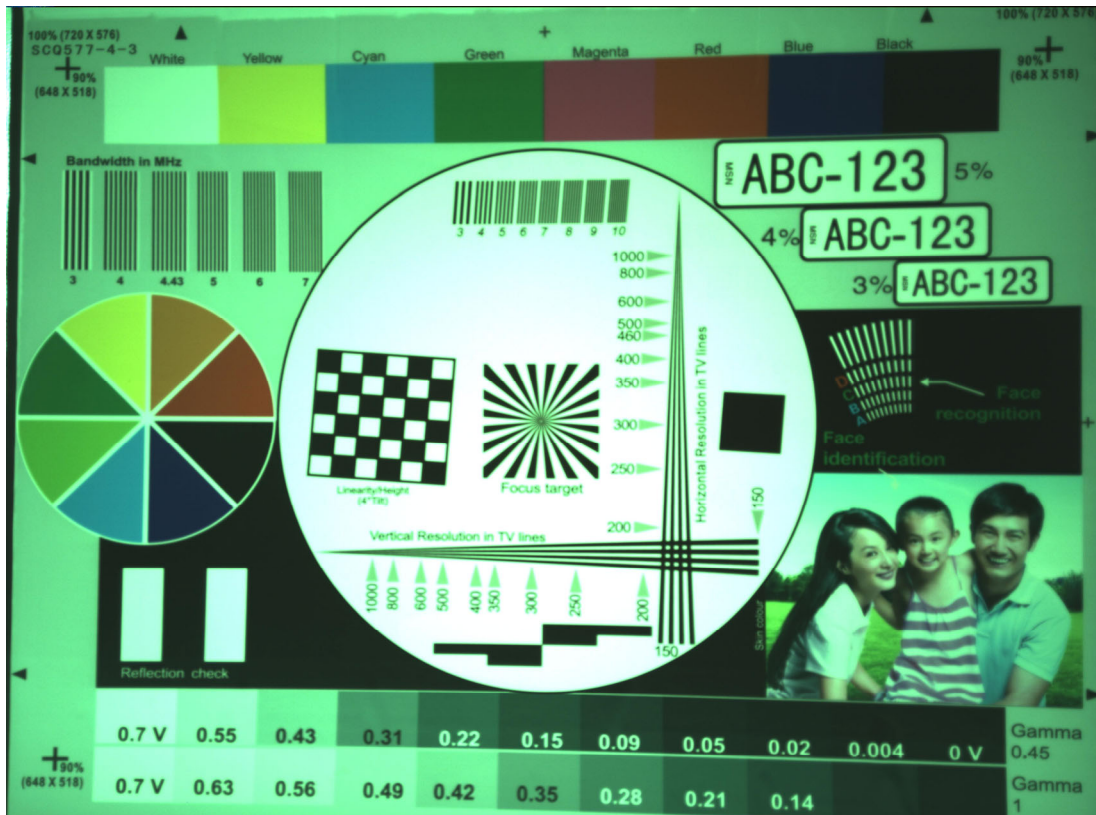
Designed By	Kevin	Model Name:	ENT-IMX214 V1.0		
Checked By	Aouly_Yan	Projection Type:	Unit: mm	Material:	
		Third Angle	Scale: 1:1	Sheet: 1 of 1	Version: 1/0

Version Mark	Information	Date
V1.0 PD	First Version	2018-12-05

Real Test Images ENT-IMX214 V1.0



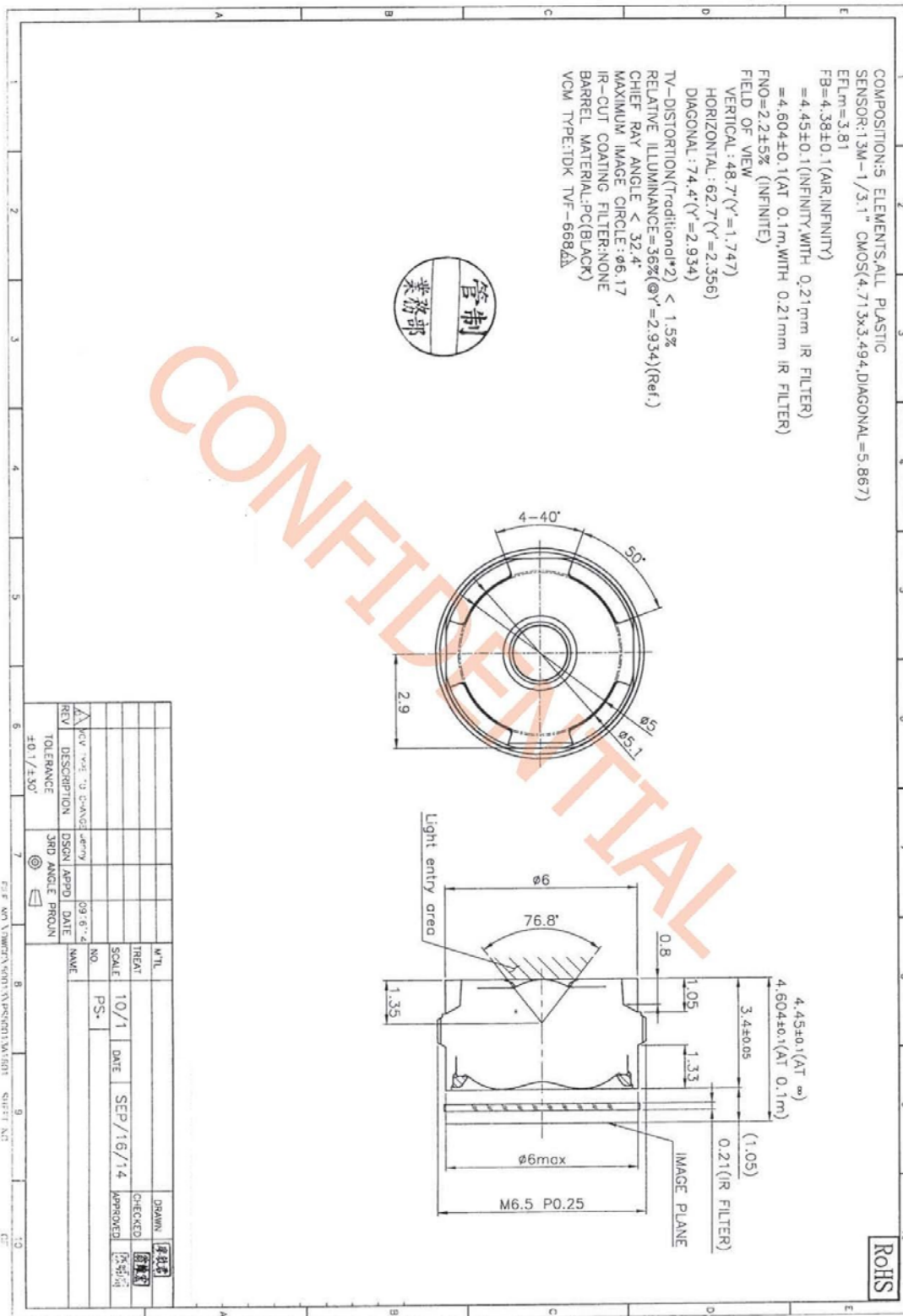
Real Test Images ENT-IMX214 V1.0



Real Test Images
ENT-IMX214 V1.0



Lens Model: KLT-LENS-50013A1



10-Bit DAC 120mA VCM Driver with I²C Interface

Description

The FP5510 is a single 10-bit DAC with 120mA output current voice coil motor (VCM) driver, with an I²C-compatible serial interface that operates at clock rates up to 400kHz. Its supply operates from 2.3V to 3.6V.

The FP5510 incorporates with a power-on reset circuit, power-down function. Power-on reset circuit ensure when supply power up, DAC output is to 0V until valid write bit value takes place. In power down mode, the supply current is about 1µA.

The FP5510 is designed for auto focus operation includes digital camera module, optical zoom camera phones and lens auto focus. The I²C address of FP5510 is 0x18h.

The FP5510 with WLCSP package which it is suitable for reduced-space mounting in mobile phone and other portable applications.

Pin Assignments

6-Ball WLCSP

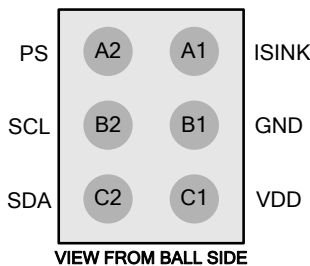


Figure 1. Pin Assignment of FP5510

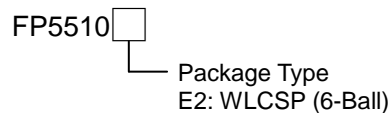
Features

- Power Supply Voltage Rang: 2.3V to 3.6V
- VCM Driver for Auto-Focus
- 10-Bit Resolution Current Sinking of 120mA for VCM
- 2-Wire I²C Interface (1.8V Interface Compatible)
- Internal 4 Slope Control Mechanism
 1. Enhance Slope Control Mode
 2. One Step Mode
 3. Linear Slope Mode
 4. Two Step Slope Mode
- Power-Save Mode Current < 1µA
- Power On Reset (POR)
- Small Size: 0.7mm×1.1mm (6-Balls WLCSP)

Applications

- Digital Camera Module
- Cell Phone
- Lens Cover
- Web Camera

Ordering Information

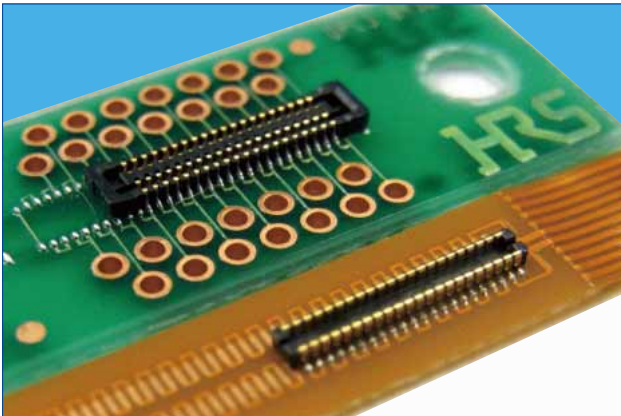


WLCSP-6 (0.7mm×1.1mm) Marking

Part Number	Product Code
FP5510E2	2

0.4mm Pitch, 0.6 and 0.8mm Height, Board-to-Board and Board-to-FPC Connectors

BM20 Series



■ Features

1. High density mounting capability

A space saving design that keeps the connector compact, but still maintains an adequate vacuum area (no less than 0.7mm wide).
Depth DS : 2.3mm DP : 1.78mm

2. Reliable contact performance

Even though the mated height is low, the BM20 still leads it class in maximum effective mating lengths for each mating height.
<Effective Mating Length>
Height 0.8mm : 0.2mm
Height 0.6mm : 0.15mm

The addition of the two point contact system adds more reliability to the contacts.

3. No restrictions to PCB pattern design for the 0.8 mm height connector *1

This series utilizes a thin wall to insulate the bottom surface of the connector and maintains an effective mating length of 0.2mm. This removes any restriction for PCB pattern layout design under the connector.

Note *1: There are some restrictions for the 0.6 mm height style.

4. Enhanced mating operations

The structure uses guide ribs to ease the mating process and offers a self alignment range of up to 0.3mm. A clear tactile click is used as an indicator to the user that the mating process was completed.

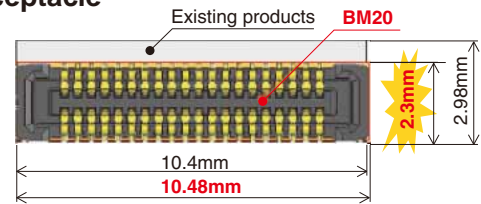
5. Drop and shock resistant structure

Dimples were designed into the contacts to increase their retention force and to absorb the shock delivered from a drop or other impact.

6. Debris resisting design

When mated, the connector's design covers the contacts which help to keep dust and other debris away from the contacts. The SMT leads are kept very close to the connector housing which also helps to prevent shorts caused by debris on the exposed contacts

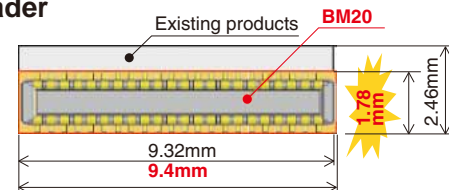
■ Receptacle



A 22.3% reduction in size!

Existing products	BM20
2.98 × 10.4 = About 31.0mm ²	2.3 × 10.48 = About 24.1mm ²

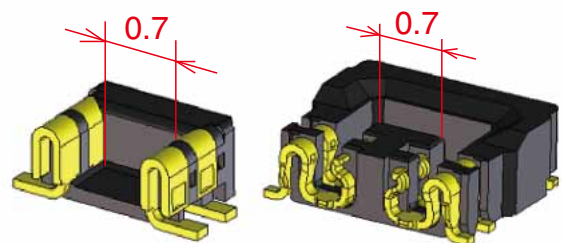
■ Header



A 27.1% reduction in size!

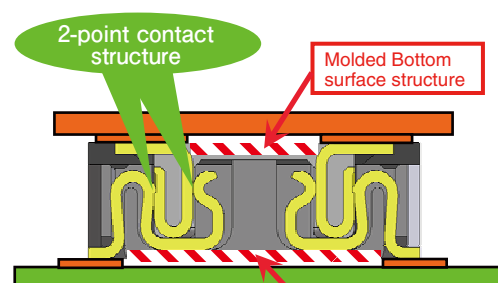
Existing products	BM20
2.46 × 9.32 = About 22.9mm ²	1.78 × 9.4 = About 16.7mm ²

Vacuum pick-up

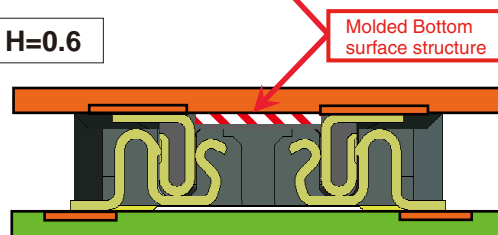


Mating diagram (cross section)

H=0.8



H=0.6



Product Specifications

Ratings	Rated Current	0.3A	Operating Temperature Range	- 35 ~ 85°C (Note 1)	Storage Temperature Range	- 10 ~ 60°C (Note 2)
	Rated Voltage	AC, DC 30V	Operating Humidity Range	20 ~ 80%	Storage Humidity Range	40 ~ 70% (Note 2)

Items	Specifications	Conditions
1. Insulation Resistance	Minimum of 50MΩ	Measured with DC 100V
2. Withstanding Voltage	No flashover or breakdown	Apply AC 100V for 1 minute
3. Contact Resistance	Maximum of 100mΩ	Measured with AC 20 mV, 1 kHz and 1 mA
4. Vibration Resistance	No electrical discontinuity of 1μs or greater	Frequency 10-55 Hz, half amplitude 0.75mm, 3 directions for 2 hours
5. Humidity Resistance	Contact resistance Maximum of 100mΩ Insulation resistance Minimum of 25mΩ	Left at temperature 40±2°C, humidity 90 to 95%, 96 hours
6. Temperature Cycles	Contact resistance Maximum of 100mΩ Insulation resistance Minimum of 50mΩ	(-55°C : 30 minutes → 5~35°C : 10 minutes → 85°C : 30 minutes → 5~35°C : 10 minutes) 5 cycles
7. Durability	Contact Resistance: maximum of 100mΩ	10 mating cycles
8. Soldering Heat Resistance	Should be no melting of resin parts that affects its performance	Reflow : according to the Recommended Solder Profile Hand solder : Soldering iron temperature 350°C, no more than 3 seconds.

Note 1 : Includes temperature rise caused by current flow.

Note 2 : The term "storage" here refers to products stored for a long period prior to board mounting and use. The operating temperature and humidity range covers the non-energized condition of connectors after board mounting and the temporary storage conditions during transportation, etc.

Materials

Product	Component	Materials	Finish	UL Regulation
Receptacle	Insulator	LCP	Black	UL94V-0
Header	Contact	Phosphorous bronze	Gold plating	—

Product Number Structure

Refer to this page when determining product specifications by model types. Please place orders with part numbers listed in this catalog. The characteristics and specifications of the product described in this catalog are reference values. Please make sure to check the latest delivery specifications at the time of product use.

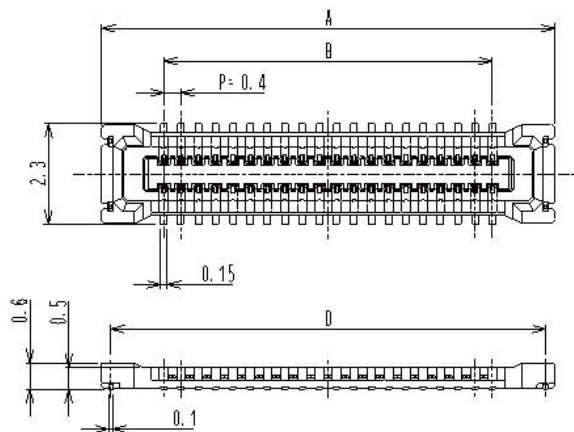
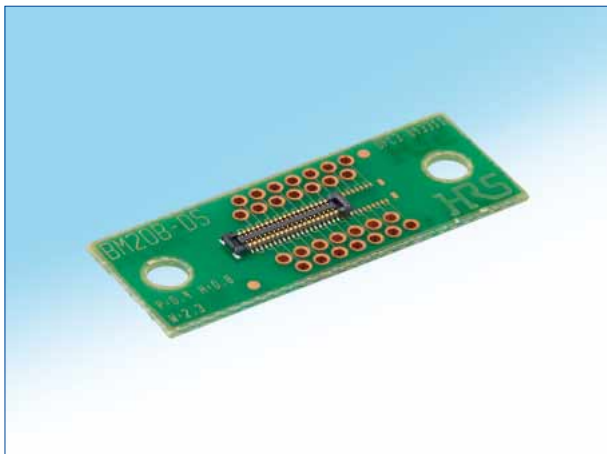
● Receptacle/Header

BM 20 # () - * DS - 0.4 V (51)**

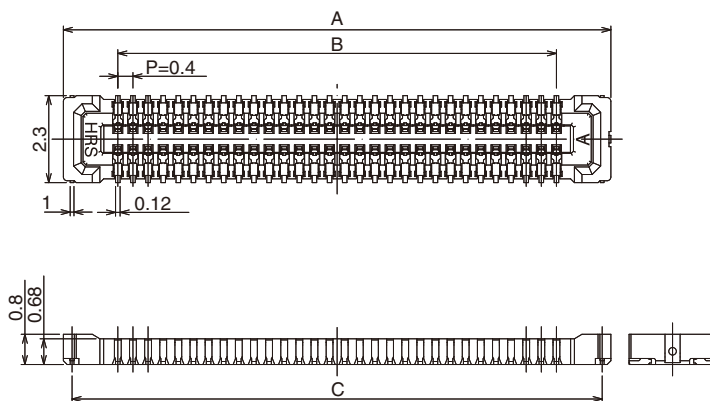
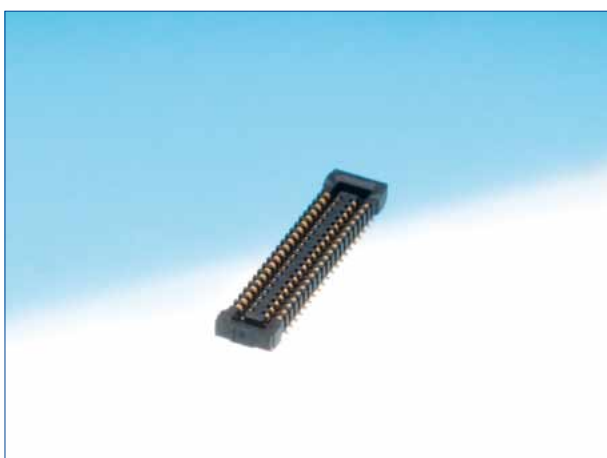
① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨

① Series Name : BM	⑥ Connector Type DS : Double row receptacle DP : Double row header
② Series No. : 20	
③ Shape Symbols B : With reinforcing metal fitting	⑦ Contact Pitch : 0.4mm
④ Stack height : 0.6mm, 0.8mm	⑧ Terminal Shape V : Vertical SMT
⑤ No. of Contacts : Please refer to page 3 and after.	⑨ Packaging (51) : Embossed tape package (8,000 pieces per reel)

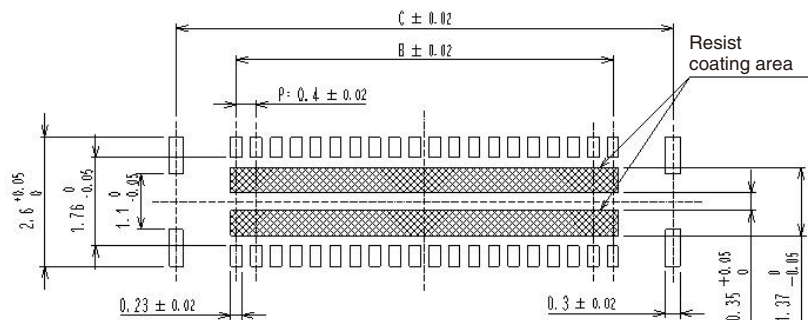
■ H=0.6mm receptacle



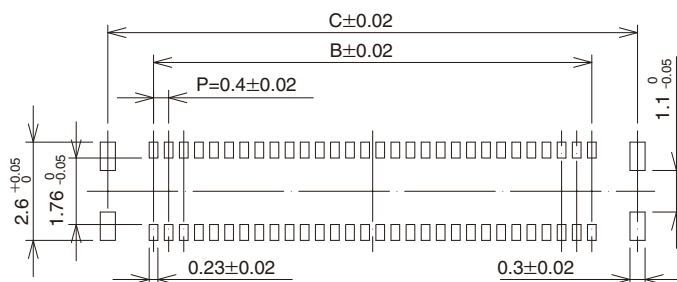
■ H=0.8mm receptacle



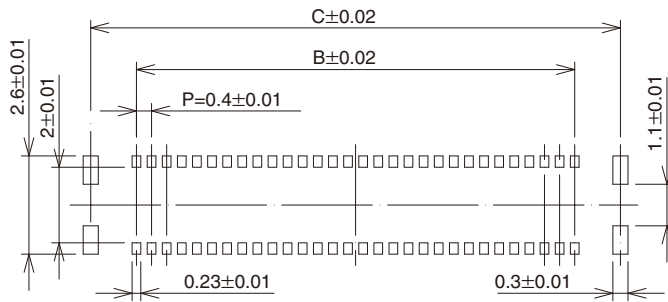
◆ Recommended PCB layout [H= 0.6mm]



◆ Recommended PCB layout [H= 0.8mm]



◆Recommended metal mask size (Mask thickness 100 μm) [0.6 mm and 0.8 mm common]



Unit : mm

Part No.	HRS No.	No. of Contacts	A	B	C	D
BM20B(0.6)-10DS-0.4V(51)	0684-9308-8 51	10	4.48	1.6	4.02	4.06
BM20B(0.6)-20DS-0.4V(51)	0684-9309-0 51	20	6.48	3.6	6.02	6.06
BM20B(0.6)-24DS-0.4V(51)	0684-9310-0 51	24	7.28	4.4	6.82	6.86
BM20B(0.6)-30DS-0.4V(51)	0684-9311-2 51	30	8.48	5.6	8.02	8.06
BM20B(0.6)-34DS-0.4V(51)	0684-9312-5 51	34	9.28	6.4	8.82	8.86
BM20B(0.6)-40DS-0.4V(51)	0684-9313-8 51	40	10.48	7.6	10.02	10.06
BM20B(0.6)-50DS-0.4V(51)	0684-9314-0 51	50	12.48	9.6	12.02	12.06
BM20B(0.6)-60DS-0.4V(51)	0684-9315-3 51	60	14.48	11.6	14.02	14.06

Part No.	HRS No.	No. of Contacts	A	B	C
BM20B(0.8)-10DS-0.4V(51)	0684-9008-4 51	10	4.48	1.6	4.02
BM20B(0.8)-16DS-0.4V(51)	0684-9041-0 51	16	5.68	2.8	5.22
BM20B(0.8)-20DS-0.4V(51)	0684-9009-7 51	20	6.48	3.6	6.02
BM20B(0.8)-24DS-0.4V(51)	0684-9010-6 51	24	7.28	4.4	6.82
BM20B(0.8)-30DS-0.4V(51)	0684-9011-9 51	30	8.48	5.6	8.02
BM20B(0.8)-34DS-0.4V(51)	0684-9020-0 51	34	9.28	6.4	8.82
BM20B(0.8)-40DS-0.4V(51)	0684-9012-1 51	40	10.48	7.6	10.02
BM20B(0.8)-50DS-0.4V(51)	0684-9013-4 51	50	12.48	9.6	12.02

Note 1 : This product is sold by full reel quantities of 8,000 pieces per reel. Please place orders in full reel quantities.

Note 2 : This connector is NOT polarized.

[Product Brief]

Ver.1.0

IMX214

Diagonal 5.867mm (Type 1/3.06) 13M Pixel CMOS Image Sensor with Square Pixel for Color Cameras

Description

IMX214 is a diagonal 5.867mm (Type 1/3.06) 13M pixel CMOS active pixel type stacked image sensor with a square pixel array. It adopts Exmor RS™ technology to achieve high speed image capturing by column parallel A/D converter circuits and high sensitivity and low noise image (comparing with conventional CMOS image sensor) through the backside illuminated imaging pixel structure. R, G, and B pigment primary color mosaic filter is employed. By introducing spacially varying exposure technology, high dynamic range still pictures and movies are achievable. It equips an electronic shutter with variable integration time. It operates with three power supply voltages: analog 2.7 V, digital 1.0V and 1.8 V for input/output interface and achieves low power consumption. IMX214 is designed for use in cellular phones or tablet devices*.

Functions and Features

- ◆ Back illuminated and stacked CMOS image sensor Exmor RS
- ◆ Single Frame High Dynamic Range (HDR) with equivalent full pixels.
- ◆ High signal to noise ratio (SNR).
- ◆ Full resolution @30fps (Normal / HDR). 4K2K @30fps (Normal / HDR) 1080p @60fps (Normal / HDR)
- ◆ Output video format of RAW10/8, COMP8/6
- ◆ Pixel binning readout and H/V sub sampling function
- ◆ Advanced Noise Reduction (Chroma noise reduction and luminance noise reduction)
- ◆ Independent flipping and mirroring.
- ◆ CSI 2 serial data output (MIPI 2lane/4lane, Max. 1.2Gbps/lane, DPHY spec. ver. 1.1 compliant)
- ◆ 2wire serial communication
- ◆ Two PLLs for independent clock generation for pixel control and data output interface.
- ◆ Advanced Noise Reduction.
- ◆ Dynamic Defect Pixel Correction.
- ◆ Zero shutter lag.
- ◆ Power on reset function
- ◆ Dual sensor synchronization operation.
- ◆ 8K bit of OTP ROM for users.
- ◆ Built in temperature sensor

NOTE)

1. When using this product for another application, Sony does not guarantee the quality and reliability of product. Therefore, don't use this for applications other than cellular phone and Tablet PCs. Consult your Sony sales representative if you have any questions.

Device Structure

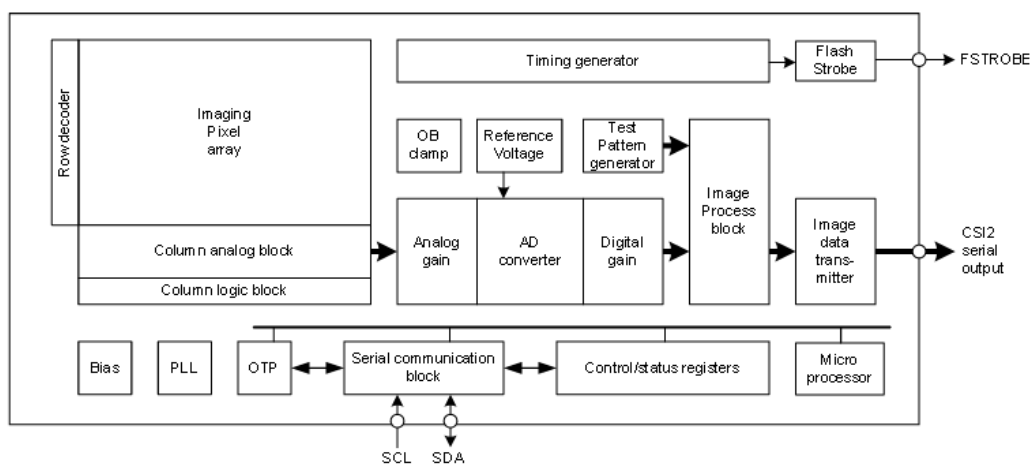
- ◆ CMOS image sensor
- ◆ Image size : Diagonal 5.867mm (Type 1/3.06)
- ◆ Total number of pixels : 4224 (H) × 3200(V) approx. 13.51M pixels
- ◆ Number of effective pixels : 4224 (H) × 3136 (V) approx. 13.25 M pixels
- ◆ Number of active pixels : 4208 (H) × 3120 (V) approx. 13.13 M pixels
- ◆ Chip size : 6.100mm (H) × 4.524mm (V)
- ◆ Unit cell size : 1.12 μm (H) × 1.12 μm (V)
- ◆ Substrate material : Silicon

Functional Description

System Outline

IMX214 is a CMOS active pixel type image sensor which adopts the Exmor RS™ technology to achieve high sensitivity, low noise and high speed image capturing. It is embedded with backside illuminated imaging pixel, low noise analog amplifier, column parallel A/D converters which enables high speed capturing, digital amplifier, image binning circuit, timing control circuit for imaging size and frame rate, CSI2 image data high speed serial interface, PLL oscillator, and serial communication interface to control these functions. Several additional image processing functions and peripheral circuits are also included for easy system optimization by the users. A one time programmable memory is embedded in the chip for storing the user data. It has 8 K-bit for users, 10 K-bit as a whole.

Block Diagram



Exmor RS

* Exmor RS is a trademark of Sony Corporation. The Exmor RS is a Sony's CMOS image sensor with high-resolution, high-performance and compact size by replacing a supporting substrate in Exmor R™ which changed fundamental structure of Exmor™ pixel adopted column parallel A/D converter to back-illuminated type, with layered chips formed signal processing circuits.

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Application circuits shown, if any, are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits.

Cameras Applications



Automotive Driver Pilot



Live Streaming



Video Conference



Eye Tracker Biometric Detection



Machine Vision



Agricultural Monitor



Night Vision Security



Drone and Sports Eagle Eyes



Interactive Pet Camera



YDS CAMERA MODULE

your best camera partner

Camera Module Pinout Definition Reference Chart

OmniVision	Sony	Samsung	On-Semi	Aptina	Himax	GalaxyCore	PixArt	SmartSens	Sensors
Pin Signal		Description							
DGND	GND	ground for digital circuit							
AGND		ground for analog circuit							
PCLK	DCK	DVP PCLK output							
XCLR	PWDN	XSHUTDOWN	STANDBY	power down active high with internal pull-down resistor					
MCLK	XVCLK	XCLK	INCK	system input clock					
RESET	RST	reset active low with internal pull-up resistor							
NC	NULL	no connect							
SDA	SIO_D	SIOD	SCCB data						
SCL	SIO_C	SIOC	SCCB input clock						
VSYNC	XVS	FSYNC	DVP VSYNC output						
HREF	XHS	DVP HREF output							
DOVDD	power for I/O circuit								
AFVDD	power for VCM circuit								
AVDD	power for analog circuit								
DVDD	power for digital circuit								
STROBE	FSTROBE	strobe output							
FSIN	synchronize the VSYNC signal from the other sensor								
SID	SCCB last bit ID input								
ILPWM	mechanical shutter output indicator								
FREX	frame exposure / mechanical shutter								
GPIO	general purpose inputs								
SLASEL	I2C slave address select								
AFEN	CEN chip enable active high on VCM driver IC								
MIPI Interface									
MDN0	DN0	MD0N	DATA_N	DMO1N	MIPI 1st data lane negative output				
MDP0	DP0	MD0P	DATA_P	DMO1P	MIPI 1st data lane positive output				
MDN1	DN1	MD1N	DATA2_N	DMO2N	MIPI 2nd data lane negative output				
MDP1	DP1	MD1P	DATA2_P	DMO2P	MIPI 2nd data lane positive output				
MDN2	DN2	MD2N	DATA3_N	DMO3N	MIPI 3rd data lane negative output				
MDP2	DP2	MD2P	DATA3_P	DMO3P	MIPI 3rd data lane positive output				
MDN3	DN3	MD3N	DATA4_N	DMO4N	MIPI 4th data lane negative output				
MDP3	DP3	MD3P	DATA4_P	DMO4P	MIPI 4th data lane positive output				
MCN	CLKN	CLK_N	DCKN	MIPI clock negative output					
MCP	CLKP	MCP	CLK_P	DCKN	MIPI clock positive output				
DVP Parallel Interface									
D0	DO0	Y0	DVP data output port 0						
D1	DO1	Y1	DVP data output port 1						
D2	DO2	Y2	DVP data output port 2						
D3	DO3	Y3	DVP data output port 3						
D4	DO4	Y4	DVP data output port 4						
D5	DO5	Y5	DVP data output port 5						
D6	DO6	Y6	DVP data output port 6						
D7	DO7	Y7	DVP data output port 7						
D8	DO8	Y8	DVP data output port 8						
D9	DO9	Y9	DVP data output port 9						
D10	DO10	Y10	DVP data output port 10						
D11	DO11	Y11	DVP data output port 11						

www.YDSCAM.com sales@ydscam.com Phone (WeChat, QQ): (+86) 177 2732 6718

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Camera Reliability Test

Reliability Inspection Item		Testing Method	Acceptance Criteria	
Category	Item			
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional



Camera Inspection Standard

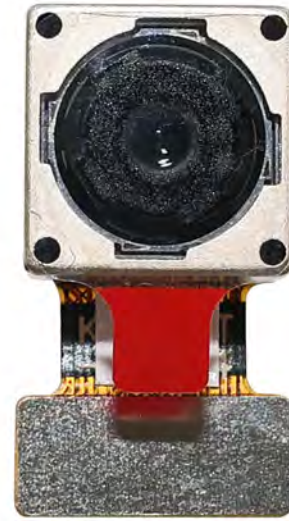
Inspection Item		Inspection Method	Standard of Inspection		
Category	Item				
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.	
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.	
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)	
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed	
		Gap	The Naked Eye	Meet the Height Standard	
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)	
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed	
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard	
		Contamination	The Naked Eye	No Effect On Resolution Standard	
		Oil Film	The Naked Eye	No Effect On Resolution Standard	
		Cover Tape	The Naked Eye	No Issue On Appearance.	
	Function	Image	No Communication	Test Board	Not Allowed
			Bright Pixel	Black Board	Not Allowed In the Image Center
Dark Pixel			White board	Not Allowed In the Image Center	
Blurry			The Naked Eye	Not Allowed	
No Image			The Naked Eye	Not Allowed	
Vertical Line			The Naked Eye	Not Allowed	
Horizontal Line			The Naked Eye	Not Allowed	
Light Leakage			The Naked Eye	Not Allowed	
Blinking Image			The Naked Eye	Not Allowed	
Bruise			Inspection Jig	Not Allowed	
Resolution			Chart	Follows Outgoing Inspection Chart Standard	
Color			The Naked Eye	No Issue	
Noise			The Naked Eye	Not Allowed	
Corner Dark			The Naked Eye	Less Than 100px By 100px	
Color Resolution			The Naked Eye	No Issue	
Dimension	Height	The Naked Eye	Follows Approval Data Sheet		
	Width	The Naked Eye	Follows Approval Data Sheet		
	Length	The Naked Eye	Follows Approval Data Sheet		
	Overall	The Naked Eye	Follows Approval Data Sheet		

YDSCAM Package Solutions

YDS Camera Module



Complete with Lens Protection Film



Tray with Grid and Space



Place Cameras on the Tray



YDSCAM Package Solutions

Full Tray of Cameras



Cover Tray with Lid



Place Tray into Anti-Static Bag



Vacuum the Anti-Static Bag



YDSCAM Package Solutions

Sealed Vacuum Anti-Static Bag with Labels

1. Model and Description 2. Quantity 3. Manufacturing Date Code 4. Caution



YDSCAM Package Solutions

Place Foam Sheets Between Tray Bags



Foam Sheets are Larger Than Trays



Place Foam Sheets and Trays into Box



Foam Sheets are Tightly Fitting in Box



Seal the Carbon Box



Label the Carbon Shipping Box

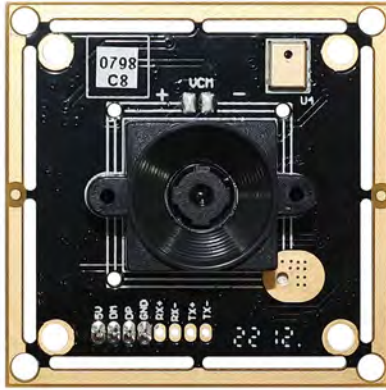




YDSCAM Package Solutions

USB Camera Module

Complete with Lens Protection Film



Place Camera Sample into Anti-Static Bag

Place USB Cameras into Tray



Seal the Tray with Anti-Static Bag

Label the Carbon Shipping Box



YDSCAM Package Solutions

Place Camera Sample into Anti-Static Bag



Place Connectors into Anti-Static Bag



Label the Sample Bags



Place Connectors into Reel



Place Samples into the Carbon Box



Place Connectors into the Carbon Box





YDS CAMERA MODULE

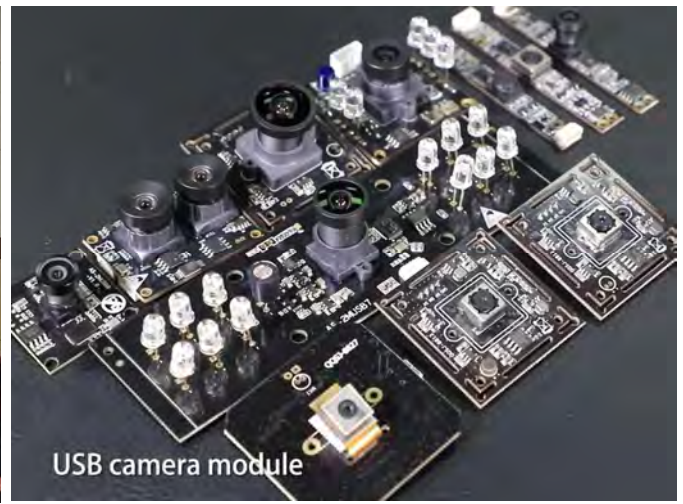
your best camera partner

Company YDSCAM

YingDeShun Co. Ltd. (YDS) was established in 2017, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. YDS is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

YDS provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. YDS specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.



Limited Warranty

YDS provides the following limited warranty if you purchased the Product(s) directly from YDS company or from YDS's website www.YDSCAM.com. Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. YDS guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, YDS will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of YDS is solely limited to repair and/or replacement on the terms set forth above. YDS is not reliable or responsible for any subsequent events.



www.YDSCAM.com sales@ydscam.com Phone (WeChat, QQ): (+86) 177 2732 6718

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YDS CAMERA MODULE

your best camera partner

YDS Strength

Powerful Factory



Professional Service



Promised Delivery



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